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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	12MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	24
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	A/D 12x14b; D/A 2x9b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c24423a-12pvxe

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



CY8C24223A, CY8C24423A

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PSoC Functional Overview

The PSoC family consists of many programmable system-on-chips with on-chip Controller devices. These devices are designed to replace multiple traditional microcontroller unit (MCU)-based system components with one, low cost single-chip programmable device. PSoC devices include configurable blocks of analog and digital logic, and programmable interconnects. This architecture enables the user to create customized peripheral configurations that match the requirements of each individual application. Additionally, a fast CPU, Flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts and packages.

The PSoC architecture, as shown in the Logic Block Diagram on page 1, is comprised of four main areas: PSoC Core, Digital System, Analog System, and System Resources. Configurable global buses allow all the device resources to be combined into a complete custom system. Each CY8C24x23A PSoC device includes four digital blocks and six analog blocks. Depending on the PSoC package, up to 24 GPIO are also included. The GPIO provide access to the global digital and analog interconnects.

PSoC Core

The PSoC Core is a powerful engine that supports a rich feature set. The core includes a CPU, memory, clocks, and configurable GPIO.

The M8C CPU core is a powerful processor with speeds up to 12 MHz, providing a two MIPS 8-bit Harvard architecture microprocessor. The CPU uses an interrupt controller with multiple vectors, to simplify programming of real time embedded events. Program execution is timed and protected using the included Sleep Timer and Watchdog Timer (WDT).

Memory includes 4 KB of Flash for program storage and 256 bytes of SRAM for data storage. Program Flash uses four protection levels on blocks of 64 bytes, allowing customized software IP protection.

The PSoC device incorporates flexible internal clock generators, including a 24 MHz IMO (internal main oscillator) accurate to $\pm 4\%$ over temperature and voltage. A low power 32 kHz internal low speed oscillator (ILO) is provided for the Sleep Timer and WDT. If crystal accuracy is desired, the ECO (32.768 kHz external crystal oscillator) is available for use as a Real Time Clock (RTC) and can optionally generate a crystal-accurate 24 MHz system clock using a PLL. The clocks, together with programmable clock dividers (as a System Resource), provide the flexibility to integrate almost any timing requirement into the PSoC device.

PSoC GPIOs provide connection to the CPU, digital, and analog resources of the device. Each pin's drive mode may be selected from eight options, allowing great flexibility in external interfacing. Every pin also has the capability to generate a system interrupt.

Digital System

The Digital System is composed of four digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user modules.





Digital peripheral configurations include:

- PWMs (8- and 16-bit)
- PWMs with Dead Band (8- and 16-bit)
- Counters (8 to 32 bit)
- Timers (8 to 32 bit)
- Full or Half-Duplex 8-bit UART with selectable parity
- SPI master and slave
- I²C master, slave, or multi-master
- Cyclical Redundancy Checker/Generator (16 bit)
- IrDA

Pseudo Random Sequence Generators (8 to 32 bit)

The digital blocks can be connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 5.





Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is summarized in four steps:

- 1. Select User Modules.
- 2. Configure User Modules.
- 3. Organize and Connect.
- 4. Generate, Verify, and Debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called "user modules." User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a PWM User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These user module datasheets explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information you may need to successfully implement your design.

Organize and Connect

You build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. You perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, you perform the "Generate Configuration Files" step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides application programming interfaces (APIs) with high-level functions to control and respond to hardware events at run-time and interrupt service routines that you can adapt as needed.

A complete code development environment allows you to develop and customize your applications in either C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's debugger (access by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer and allows you to define complex breakpoint events. These include monitoring address and data bus values, memory locations, and external signals.



Document Conventions

Acronyms Used

The following table lists the acronyms that are used in this document.

Table 2. Acronyms

Acronym	Description							
AC	alternating current							
ADC	analog-to-digital converter							
API	application programming interface							
CPU	central processing unit							
СТ	continuous time							
DAC	digital-to-analog converter							
DC	direct current							
ECO	external crystal oscillator							
EEPROM	electrically erasable programmable read-only memory							
FSR	full scale range							
GPIO	general purpose I/O							
GUI	graphical user interface							
HBM	human body model							
ICE	in-circuit emulator							
ILO	internal low speed oscillator							
IMO	internal main oscillator							
I/O	input/output							
IPOR	imprecise power on reset							
LSb	least-significant bit							
LVD	low voltage detect							
MSb	most-significant bit							
PC	program counter							
PLL	phase-locked loop							
POR	power on reset							
PPOR	precision power on reset							
PSoC®	Programmable System-on-Chip							
PWM	pulse width modulator							
SC	switched capacitor							
SRAM	static random access memory							

Units of Measure

A units of measure table is located in the Electrical Specifications section. Table 8 on page 14 lists all the abbreviations used to measure the PSoC devices.

Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or '0x' are decimal.



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28-Pin Part Pinout

Table 4. 28-Pin Part Pinout (SSOP)

Pin	Ту	pe	Pin	Description						
No.	Digital	Analog	Name	Description						
1	I/O	Ι	P0[7]	Analog column mux input						
2	I/O	I/O	P0[5]	Analog column mux input and column						
				output						
3	I/O	I/O	P0[3]	Analog column mux input and column output						
4	I/O	I	P0[1]	Analog column mux input						
5	I/O		P2[7]							
6	I/O		P2[5]							
7	I/O	-	P2[3]	Direct switched capacitor block input						
8	I/O	Ι	P2[1]	Direct switched capacitor block input						
9	Po	wer	Vss	Ground connection						
10	I/O		P1[7]	I ² C Serial Clock (SCL)						
11	I/O		P1[5]	I ² C Serial Data (SDA)						
12	I/O		P1[3]							
13	I/O		P1[1]	Crystal Input (XTALin), I ² C Serial Clock (SCL), ISSP-SCLK ^[5]						
14	Power		Vss	Ground connection						
15	I/O		P1[0]	Crystal Output (XTALout), I ² C Serial Data (SDA), ISSP-SDATA ^[5]						
16	I/O		P1[2]							
17	I/O		P1[4]	Optional External Clock Input (EXTCLK)						
18	I/O		P1[6]							
19	Inj	put	XRES	Active high external reset with internal pull down						
20	I/O	I	P2[0]	Direct switched capacitor block input						
21	I/O	I	P2[2]	Direct switched capacitor block input						
22	I/O		P2[4]	External Analog Ground (AGND)						
23	I/O		P2[6]	External Voltage Reference (VRef)						
24	I/O	I	P0[0]	Analog column mux input						
25	I/O	I	P0[2]	Analog column mux input						
26	I/O	Ι	P0[4]	Analog column mux input						
27	I/O	Ι	P0[6]	Analog column mux input						
28	Po	wer	Vdd	Supply voltage						

Figure 4. CY8C24423A 28-Pin PSoC Device



LEGEND: A = Analog, I = Input, and O = Output.



Registers

Register Conventions

This section lists the registers of the automotive CY8C24x23A PSoC device. For detailed register information, refer to the *PSoC Technical Reference Manual*.

The register conventions specific to this section are listed in the following table.

Table 5. Abbreviations

Convention Description							
R	Read register or bit(s)						
W	Write register or bit(s)						
L	Logical register or bit(s)						
С	Clearable register or bit(s)						
#	Access is bit specific						

Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks. The XIO bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XIO bit is set the user is in Bank 1.

Note In the following register mapping tables, blank fields are Reserved and must not be accessed.



Table 6. Register Map Bank 0 Table: User Space

Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW		40		ASC10CR0	80	RW		C0	
PRT0IE	01	RW		41		ASC10CR1	81	RW		C1	
PRT0GS	02	RW		42		ASC10CR2	82	RW		C2	
PRT0DM2	03	RW		43		ASC10CR3	83	RW		C3	
PRT1DR	04	RW		44		ASD11CR0	84	RW		C4	
PRT1IE	05	RW		45		ASD11CR1	85	RW		C5	
PRT1GS	06	RW		46		ASD11CR2	86	RW		C6	
PRT1DM2	07	RW		47		ASD11CR3	87	RW		C7	
PRT2DR	08	RW		48			88			C8	
PRT2IE	09	RW		49			89			C9	
PRT2GS	0A	RW		4A			8A			CA	
PRT2DM2	0B	RW		4B			8B			CB	
	0C			4C			8C			CC	
	0D			4D			8D			CD	
	0E			4E			8E			CE	
	0F			4F			8F			CF	
	10			50		ASD20CR0	90	RW		D0	
	11			51		ASD20CR1	91	RW		D1	
	12			52		ASD20CR2	92	RW		D2	
	13			53		ASD20CR3	93	RW		D3	
	14			54		ASC21CR0	94	RW		D4	
	15			55		ASC21CR1	95	RW		D5	
	16			56		ASC21CR2	96	RW	I2C CEG	D6	RW
	17			57		ASC21CR3	97	RW	120_01 0	D7	#
	18		-	58		70021010	98	1.00	120_001	D8	# RW
	10		-	59			90		I2C_MSCR	D9	#
	10			50			95				# RW/
	1A 1B			5R			9A 9B		INT_CLR1	DR	RW
	10			5C			90				1.00
	10			50 5D							DW/
	1D 1E			55			9D 0E		INT_OLIKS	DE	RW/
	15			55			9L 0E			DE	1110
	20	#	ΔΜΧ ΙΝΙ	60	D\//		<u>عام 20</u>		INT MSKO	EO	DW/
	20	# \\\/		61	NVV		A0		INT_WSRU	L0 E1	DW/
DBB00DR1	21			62			A1 A2			E1	RW BC
DBB00DR2	22	#	ADE CD	62			A2		DES WOT	E2	W
	23	#	ARF_CR	64	#		A3			E3	NV DC
	24	# \\\/	CIVIF_CRU	65	#		A4			E4	RC BC
	20			00	#		AG		DEC_DL	EJ	
DBB01DR2	20	KW	CIVIP_CRI	67	RW		A0		DEC_CRU	E0	RW
DBBUICRU	27	#		67			A7			E7	RW
	20	#		00 60			A0			E0	VV VV
DCB02DRT	29			69			A9		MUL_T	E9	VV
DCB02DR2	2A 2D	RW	-	6A			AA		MUL_DH	EA	R
DCB02CR0	2B	#	-	6B			AB		MUL_DL	EB	R
DCB03DR0	20	#	-	6C			AC		ACC_DR1	EC	RW
DCB03DR1	2D 25	VV		٥D			AD		ACC_DRU		
DCB03DR2	2E	KVV		0E			AE		ACC_DR3		KW DW
DCB03CR0	2F	#	1000000	6F	D14/	DDIADI	AF	DIM	ACC_DR2	EF	RW
	30		ACBUUCR3	/0	RW		R0	RW		F0	
	31		ACBOOCRO	71	RW	RDIUSYN	B1	RW		F1	
	32		ACB00CR1	72	RW	RDIOIS	B2	RW		F2	
	33		ACB00CR2	73	RW	RDIOLT0	B3	RW		F3	
	34		ACBUTCR3	/4	RW		В4 В5	RW		F4	
	35		ACB01CR0	/5	RW	KDIUKO0	B5	RW		+5	
	36		ACB01CR1	/6	RW	KDIUKO1	B6	RW		<u>⊢6</u>	<u> </u>
	37		ACB01CR2	77	RW		B7		CPU_F	F7	RL
	38			78			B8			F8	
	39			79			B9			F9	
	3A			7A			BA			FA	
	3B			7B			BB			FB	
	3C			7C			BC			FC	
	3D			7D			BD			FD	
	3E			7E			BE		CPU_SCR1	FE	#
	3F			7F			BF		CPU_SCR0	FF	#

Blank fields are Reserved and must not be accessed.

Access is bit specific.



Table 7. Register Map Bank 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW		40		ASC10CR0	80	RW		C0	
PRT0DM1	01	RW		41		ASC10CR1	81	RW		C1	
PRT0IC0	02	RW		42		ASC10CR2	82	RW		C2	
PRT0IC1	03	RW		43		ASC10CR3	83	RW		C3	
PRT1DM0	04	RW		44		ASD11CR0	84	RW		C4	
PRT1DM1	05	RW		45		ASD11CR1	85	RW		C5	
PRT1IC0	06	RW		46		ASD11CR2	86	RW		C6	
PRT1IC1	07	RW		47		ASD11CR3	87	RW		C7	
PRT2DM0	08	RW		48			88			C8	
PRT2DM1	09	RW		49			89			C9	
PRT2IC0	0A	RW		4A			8A			CA	
PRT2IC1	0B	RW		4B			8B			CB	
	0C			4C			8C			CC	
	0D			4D			8D			CD	
	0E			4E			8E			CE	
	0F			4F			8F			CF	
	10			50		ASD20CR0	90	RW	GDI_O_IN	D0	RW
	11			51		ASD20CR1	91	RW	GDI_E_IN	D1	RW
	12			52		ASD20CR2	92	RW	GDI_O_OU	D2	RW
	13			53		ASD20CR3	93	RW	GDI_E_OU	D3	RW
	14			54		ASC21CR0	94	RW		D4	
	15			55		ASC21CR1	95	RW		D5	
	16			56		ASC21CR2	96	RW		D6	
	1/			57		ASC21CR3	97	RW		D7	
	18			58			98			D8	
	19		-	59			99			D9	
	1A 1D			5A 5D			9A			DA	
	1B			3B EC			9B			DB	
	10			5C			90				D\M/
	10			50			9D		030_60_EN		
	16			5E			9E		OSC_CR4	DE	
	20	PW/		60	D\//		91			EO	RW RW
DBB00IN	20	RW		61	RW		Δ1		OSC_CR1	E0 E1	RW
DBB000U	22	RW	ABE_CR0	62	RW		A2		OSC_CR2	F2	RW
BBB0000	23		AMD_CR0	63	RW		A3		VLT CR	E3	RW
DBB01FN	24	RW		64			A4		VLT_CMP	E4	R
DBB01IN	25	RW		65			A5			E5	
DBB01OU	26	RW	AMD CR1	66	RW		A6			E6	
	27		ALT CR0	67	RW		A7			E7	
DCB02FN	28	RW	_	68			A8		IMO TR	E8	W
DCB02IN	29	RW		69			A9		ILO_TR	E9	W
DCB02OU	2A	RW		6A			AA		BDG_TR	EA	RW
	2B			6B			AB		ECO_TR	EB	W
DCB03FN	2C	RW		6C			AC			EC	
DCB03IN	2D	RW		6D			AD			ED	
DCB03OU	2E	RW		6E			AE			EE	
	2F			6F			AF			EF	
	30		ACB00CR3	70	RW	RDIORI	B0	RW		F0	
	31		ACB00CR0	71	RW	RDIOSYN	B1	RW		F1	
	32		ACB00CR1	72	RW	RDIOIS	B2	RW		F2	
	33		ACB00CR2	73	RW	RDIOLT0	B3	RW		F3	
	34		ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
	35		ACB01CR0	75	RW	RDIOROO	B5	RW		F5	
	36		ACBU1CR1	/6	RW	KUIUKU1	B6	RW		F6	6
	37		ACB01CR2	//	RW		B7		CPU_F	F/	KL
	38			/8			88			F8	
	39			/9			R9			F9	
	3A 2D			/A			BA	-		FA	
	3B			7C			BB BC			L R	
	30			70			BC				
	35			75			BE		CPU SCP1	FE	#
	3E			7E			BF		CPU SCR0	FF	#
L				11		L <u></u>			0.0_0010		77

Blank fields are Reserved and must not be accessed.

Access is bit specific.



Electrical Specifications

This section presents the DC and AC electrical specifications of the automotive CY8C24x23A PSoC device. For the latest electrical specifications, visit http://www.cypress.com.

Specifications are valid for -40°C \leq T_A \leq 125°C and T_J \leq 135°C, except where noted.



Figure 5. Voltage versus CPU Frequency

The following table lists the units of measure that are used in this section.

Table 8. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	μVrms	microvolts root-mean-square
dB	decibels	μW	microwatts
fF	femto farad	mA	milli-ampere
Hz	hertz	ms	milli-second
KB	1024 bytes	mV	milli-volts
Kbit	1024 bits	nA	nanoampere
kHz	kilohertz	ns	nanosecond
kΩ	kilohm	nV	nanovolts
Mbaud	megabaud	Ω	ohm
Mbps	megabits per second	pА	picoampere
MHz	megahertz	pF	picofarad
MΩ	megaohm	рр	peak-to-peak
μA	microampere	ppm	parts per million
μF	microfarad	ps	picosecond
μH	microhenry	sps	samples per second
μs	microsecond	σ	sigma: one standard deviation
μV	microvolts	V	volts



Table 12. DC GPIO Specifications (continued)

Symbol	Description	Min	Тур	Max	Units	Notes
V _{IH}	Input High Level	2.1	-		V	
V _H	Input Hysterisis	-	60	-	mV	
IIL	Input Leakage (Absolute Value)	-	1	-	nA	Gross tested to 1 µA
C _{IN}	Capacitive Load on Pins as Input	-	3.5	10	pF	Package and pin dependent. Temp = 25°C
C _{OUT}	Capacitive Load on Pins as Output	-	3.5	10	pF	Package and pin dependent. Temp = 25°C

DC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

The Operational Amplifier is a component of both the Analog Continuous Time (CT) PSoC blocks and the Analog Switched Capacitor (SC) PSoC blocks. The guaranteed specifications are measured in the Analog Continuous Time (CT) PSoC blocks.

Table 13. DC Operational Amplifier Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{OSOA}	Input Offset Voltage (absolute value) Low Power Input Offset Voltage (absolute value) Mid Power Input Offset Voltage (absolute value) High Power	_ _ _	1.6 1.3 1.2	11 9 9	mV mV mV	
TCV _{OSOA}	Input Offset Voltage Drift	-	7.0	35.0	μV/°C	
I _{EBOA}	Input Leakage Current (Port 0 Analog Pins)	-	200	-	pА	Gross tested to 1 µA
C _{INOA}	Input Capacitance (Port 0 Analog Pins)	-	4.5	9.5	pF	Package and pin dependent. Temp = 25°C.
V _{CMOA}	Common Mode Voltage Range Common Mode Voltage Range (high power or high opamp bias)	0.0 0.5		Vdd Vdd - 0.5	V _	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
G _{OLOA}	Open Loop Gain Power = Low Power = Medium Power = High		80 80 80		dB dB dB	Specification is applicable at high power. For all other bias modes (except high power, high opamp bias), minimum is 60 dB.
V _{OHIGHOA}	High Output Voltage Swing (worst case internal load) Power = Low Power = Medium Power = High	Vdd - 0.2 Vdd - 0.2 Vdd - 0.5	_ _ _	- - -	V V V	
V _{OLOWOA}	Low Output Voltage Swing (worst case internal load) Power = Low Power = Medium Power = High		_ _ _	0.2 0.2 0.5	V V V	
I _{SOA}	Supply Current (including associated AGND buffer) Power = Low, Opamp Bias = Low Power = Low, Opamp Bias = High Power = Medium, Opamp Bias = Low Power = Medium, Opamp Bias = High Power = High, Opamp Bias = Low Power = High, Opamp Bias = High	- - - - - -	150 300 600 1200 2400 4600	200 400 800 1600 3200 6400	μΑ μΑ μΑ μΑ μΑ	
PSRR _{OA}	Supply Voltage Rejection Ratio	_	80	_	dB	$Vss \le VIN \le (Vdd - 2.25)$ or $(Vdd - 1.25V) \le VIN \le Vdd$



DC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 14. DC Low Power Comparator Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{REFLPC}	Low power comparator (LPC) reference voltage range	0.2	-	Vdd - 1	V	
I _{SLPC}	LPC supply current	-	10	40	μA	
V _{OSLPC}	LPC voltage offset	-	2.5	30	mV	

DC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 15. DC Analog Output Buffer Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
V _{OSOB}	Input Offset Voltage (Absolute Value)	-	3	18	mV	
TCV _{OSOB}	Input Offset Voltage Drift	-	+6	-	μV/°C	
V _{CMOB}	Common-Mode Input Voltage Range	0.5	-	Vdd - 1.0	V	
R _{OUTOB}	Output Resistance	-	1	-	Ω	
V _{OHIGHOB}	High Output Voltage Swing (Load = 32Ω to Vdd/2)	0.5 x Vdd + 1.1	-	-	V	
V _{OLOWOB}	Low Output Voltage Swing (Load = 32Ω to Vdd/2)	_	Ι	0.5 x Vdd - 1.3	V	
I _{SOB}	Supply Current Including Bias Cell (No Load) Power = Low Power = High		1.1 2.6	5.1 8.8	mA mA	
PSRR _{OB}	Supply Voltage Rejection Ratio	-	64	-	dB	

















Figure 9. 24 MHz Period Jitter (IMO) Timing Diagram



Figure 10. 32 kHz Period Jitter (ECO) Timing Diagram





AC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C $\leq T_A \leq 125^{\circ}$ C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 23. AC Low Power Comparator Specifications

Symbol	Description	Min	Тур	Мах	Units	Notes
T _{RLPC}	LPC response time	-	-	50	μS	≥ 50 mV overdrive comparator
						reference set within V _{REFLPC} .

When bypassed by a capacitor on P2[4], the noise of the analog ground signal distributed to each block is reduced by a factor of up to 5 (14 dB). This is at frequencies above the corner frequency defined by the on-chip 8.1k resistance and the external capacitor.



Figure 12. Typical AGND Noise with P2[4] Bypass

At low frequencies, the opamp noise is proportional to 1/f, power independent, and determined by device geometry. At high frequencies, increased power level reduces the noise spectrum level.



Figure 13. Typical Opamp Noise



AC Digital Block Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Function	Description	Min	Тур	Max	Units	Notes
All Functions	Maximum Block Clocking Frequency	-	-	24.96 ^[12]	MHz	
Timer	Capture Pulse Width	50 ^[14]	-	-	ns	
	Maximum Frequency, No Capture	-	-	24.96 ^[12]	MHz	
	Maximum Frequency, With Capture	-	-	24.96 ^[12]	MHz	
Counter	Enable Pulse Width	50 ^[14]	-	-	ns	
	Maximum Frequency, No Enable Input	-	-	24.96 ^[12]	MHz	
	Maximum Frequency, Enable Input	-	-	24.96 ^[12]	MHz	
Dead Band	Kill Pulse Width:					
	Asynchronous Restart Mode	20	_	-	ns	
	Synchronous Restart Mode	50 ^[14]	-	_	ns	
	Disable Mode	50 ^[14]	-	-	ns	
	Maximum Frequency	-	-	24.96 ^[12]	MHz	
CRCPRS (PRS Mode)	Maximum Input Clock Frequency	-	-	24.96 ^[12]	MHz	
CRCPRS (CRC Mode)	Maximum Input Clock Frequency	-	-	24.96 ^[12]	MHz	
SPIM	Maximum Input Clock Frequency	-	-	4.16 ^[12]	MHz	Maximum data rate is 2.08 Mbps due to 2 x over clocking.
SPIS	Maximum Input Clock Frequency	-	-	2.08 ^[12]	MHz	
	Width of SS_Negated Between Transmissions	50 ^[14]	-	-	ns	
Transmitter	Maximum Input Clock Frequency	-	-	8.32 ^[12]	MHz	Maximum baud rate is 1.04 Mbaud due to 8 x over clocking.
Receiver	Maximum Input Clock Frequency	-	-	24.96 ^[12]	MHz	Maximum baud rate is 3.12 Mbaud due to 8 x over clocking.

Table 24. AC Digital Block Specifications

Note

14.50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).



AC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 25.	AC Analog	Output Buffer	Specifications
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Symbol	Description	Min	Тур	Max	Units
T _{ROB}	Rising Settling Time to 0.1%, 1V Step, 100 pF Load Power = Low Power = High	-	-	3	μs us
Т _{SOB}	Falling Settling Time to 0.1%, 1V Step, 100 pF Load Power = Low Power = High			3 3	μs μs
SR _{ROB}	Rising Slew Rate (20% to 80%), 1V Step, 100 pF Load Power = Low Power = High	0.6 0.6			V/μs V/μs
SR _{FOB}	Falling Slew Rate (80% to 20%), 1V Step, 100 pF Load Power = Low Power = High	0.6 0.6			V/μs V/μs
BW _{OB}	Small Signal Bandwidth, 20mV _{pp} , 3dB BW, 100 pF Load Power = Low Power = High	0.8 0.8		_ _	MHz MHz
BW _{OB}	Large Signal Bandwidth, 1V _{pp} , 3dB BW, 100 pF Load Power = Low Power = High	300 300		-	kHz kHz

AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C $\leq T_A \leq 125$ °C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 26. AC External Clock Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
FOSCEXT	Frequency	0.093	—	24.24	MHz	
-	High Period	20.6	_	-	ns	
-	Low Period	20.6	-	-	ns	
-	Power Up IMO to Switch	150	-	-	μS	

AC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C $\leq T_A \leq 125$ °C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 27. AC Programming Specifications

Symbol	Description	Min	Тур	Max	Units	Notes
T _{RSCLK}	Rise Time of SCLK	1	-	20	ns	
T _{FSCLK}	Fall Time of SCLK	1	-	20	ns	
T _{SSCLK}	Data Set up Time to Falling Edge of SCLK	40	-	-	ns	
T _{HSCLK}	Data Hold Time from Falling Edge of SCLK	40	-	-	ns	
F _{SCLK}	Frequency of SCLK	0	-	8	MHz	
T _{ERASEB}	Flash Erase Time (Block)	-	20	80 ^[9]	ms	
T _{WRITE}	Flash Block Write Time	-	80	320 ^[9]	ms	
T _{DSCLK}	Data Out Delay from Falling Edge of SCLK	-	-	50	ns	
T _{PRGH}	Total Flash Block Program Time (T _{ERASEB} + T _{WRITE}), Hot	_	-	200 ^[9]	ms	$T_J \ge 0^{\circ}C$
T _{PRGC}	Total Flash Block Program Time (T _{ERASEB} + T _{WRITE}), Cold	_	_	400 ^[9]	ms	T _J < 0°C



AC I²C Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75V to 5.25V and -40°C \leq T_A \leq 125°C. Typical parameters apply to 5V at 25°C and are for design guidance only.

Table 28. AC Characteristics of the I²C SDA and SCL Pins

Symbol	Description	Standar	rd Mode	Fast	Unite	
Symbol	Description	Min	Max	Min	Max	Units
F _{SCLI2C}	SCL Clock Frequency	0	100 ^[15]	0	400 ^[15]	kHz
T _{HDSTAI2C}	Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	4.0	_	0.6	_	μS
T _{LOWI2C}	LOW Period of the SCL Clock	4.7	-	1.3	-	μS
T _{HIGHI2C}	HIGH Period of the SCL Clock	4.0	-	0.6	-	μS
T _{SUSTAI2C}	Setup Time for a Repeated START Condition	4.7	-	0.6	-	μS
T _{HDDATI2C}	Data Hold Time	0	-	0	-	μS
T _{SUDATI2C}	Data Setup Time	250	-	100 ^[16]	-	ns
T _{SUSTOI2C}	Setup Time for STOP Condition	4.0	-	0.6	-	μS
T _{BUFI2C}	Bus Free Time Between a STOP and START Condition	4.7	-	1.3	-	μS
T _{SPI2C}	Pulse Width of spikes are suppressed by the input filter.	-	-	0	50	ns





Notes

16. A Fast-Mode I²C-bus device can be used in a Standard-Mode I²C-bus system, but the requirement T_{SUDATI2C} ≥ 250 ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t_{rmax} + T_{SUDATI2C} = 1000 + 250 = 1250 ns (according to the Standard-Mode I²C-bus specification) before the SCL line is released.

^{15.} F_{SCLI2C} is derived from SysClk of the PSoC. This specification assumes that SysClk is operating at 24 MHz, nominal. If SysClk is at a lower frequency, then the F_{SCLI2C} specification adjusts accordingly.



Packaging Information

This section illustrates the packaging specifications for the automotive CY8C24x23A PSoC device, along with the thermal impedances for each package and the typical package capacitance on crystal pins.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at http://www.cypress.com.



Figure 15. 20-Pin (210-Mil) SSOP





Thermal Impedances

Package	Typical θ _{JA} ^[17]
20 SSOP	117 °C/W
28 SSOP	101 °C/W

Capacitance on Crystal Pins

Package	Package Capacitance			
20 SSOP	2.6 pF			
28 SSOP	2.8 pF			

Solder Reflow Specifications

The following table shows the solder reflow temperature limits that must not be exceeded.

Package	Maximum Time above T _C – 5 °C	Maximum Peak Temperature
20 SSOP	30 seconds	260°C
28 SSOP	30 seconds	260°C

Note 17. $T_J = T_A + POWER \times \theta_{JA}$





Device Programmers

All device programmers can be purchased from the Cypress Online Store.

CY3210-MiniProg1

The CY3210-MiniProg1 kit allows a user to program PSoC devices via the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC via a provided USB 2.0 cable. The kit includes:

- MiniProg Programming Unit
- MiniEval Socket Programming and Evaluation Board
- 28-Pin CY8C29466-24PXI PDIP PSoC Device Sample
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

Accessories (Emulation and Programming)

Table 29. Emulation and Programming Accessories

CY3207ISSP In-System Serial Programmer (ISSP)

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production-programming environment.

Note: CY3207ISSP needs special software and is not compatible with PSoC Programmer. This software is free and can be downloaded from http://www.cypress.com. The kit includes:

- CY3207 Programmer Unit
- PSoC ISSP Software CD
- 110 ~ 240V Power Supply, Euro-Plug Adapter
- USB 2.0 Cable

Part Number	Pin Package	Pod Kit ^[18]	Foot Kit ^[19]	Adapter ^[20]
CY8C24223A-12PVXE	20 SSOP	CY3250-24X23A	CY3250-20SSOP-FK	Adapters can be found at
CY8C24423A-12PVXE	28 SSOP	CY3250-24X23A	CY3250-28SSOP-FK	http://www.emulation.com.

Notes

- 19. Foot kit includes surface mount feet that can be soldered to the target PCB.
- 20. Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at http://www.emulation.com.

^{18.} Pod kit contains an emulation pod, a flex-cable (connects the pod to the ICE), two feet, and device samples.



Ordering Information

The following table lists the automotive CY8C24x23A PSoC device group's key package features and ordering codes.

Package	Ordering Code	Flash (Bytes)	RAM (Bytes)	Switch Mode Pump	Temperature Range	Digital Blocks	Analog Blocks	Digital I/O Pins	Analog Inputs	Analog Outputs	XRES Pin
20 Pin (210 Mil) SSOP	CY8C24223A-12PVXE	4K	256	No	-40°C to +125°C	4	6	16	8	2	Yes
20 Pin (210 Mil) SSOP (Tape and Reel)	CY8C24223A-12PVXET	4K	256	No	-40°C to +125°C	4	6	16	8	2	Yes
28 Pin (210 Mil) SSOP	CY8C24423A-12PVXE	4K	256	No	-40°C to +125°C	4	6	24	12 ^[1]	2	Yes
28 Pin (210 Mil) SSOP (Tape and Reel)	CY8C24423A-12PVXET	4K	256	No	-40°C to +125°C	4	6	24	12 ^[1]	2	Yes

Ordering Code Definitions

CY 8 C 24 xxx-12xx

